

SY89851U



Low Power, 3GHz, 1:2 LVPECL Fanout Buffer/Translator with Internal Termination



Precision Edge®

General Description

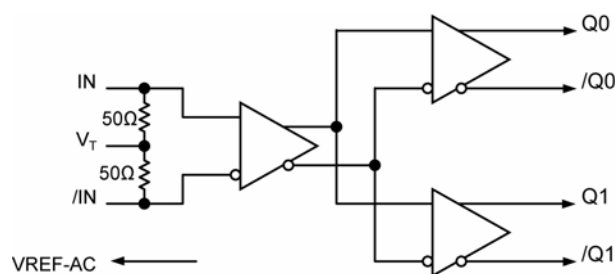
The SY89851U is a low jitter, low skew, high-speed 1:2 differential fanout buffer optimized for precision telecom and enterprise server distribution applications. The SY89851U distributes clock frequencies from DC to >3GHz, and data rates to 2.5Gbps guaranteed over temperature and voltage.

The SY89851U differential input includes Micrel's unique, 3-pin input termination architecture that directly interfaces to any differential signal (AC- or DC-coupled) as small as 100mV (200mVpp) without any level shifting or termination resistor networks in the signal path. The outputs are 800mV, 100K-compatible LVPECL with extremely fast rise/fall time guaranteed to be less than 180ps.

The SY89851U operates from a 2.5V $\pm 5\%$ or 3.3V $\pm 10\%$ supply and is guaranteed over the full industrial temperature range of -40°C to $+85^{\circ}\text{C}$. The SY89851U is part of Micrel's high-speed, Precision Edge® product line.

All support documentation can be found on Micrel's web site at www.micrel.com.

Functional Block Diagram



Features

- Precision 1:2, 800mV LVPECL fanout buffer
- Low power consumption: 80mW typ. (2.5V)
- Guaranteed AC performance over temperature and voltage:
 - DC to >3GHz clock throughput
 - <340ps propagation delay
 - <180ps rise/fall time
 - <20ps output-to-output skew
- Ultra-low jitter design:
 - <1ps_{RMS} random jitter
 - <10ps_{PP} deterministic jitter
 - <10ps_{PP} total jitter (clock)
- Unique, patented input termination and VT pin accepts DC- and AC-coupled inputs (CML, LVPECL, LVDS)
- 100K LVPECL-compatible outputs
- Power supply 2.5V $\pm 5\%$ or 3.3V $\pm 10\%$
- -40°C to $+85^{\circ}\text{C}$ industrial temperature range
- Available in 16-pin (3mm x 3mm) MLF™ package

Applications

- All SONET and GigE clock distribution
- Fibre Channel applications
- Backplane distribution
- High-end, low skew, multiprocessor synchronous clock distribution

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M9999-071205
hbwhelp@micrel.com or (408) 955-1690

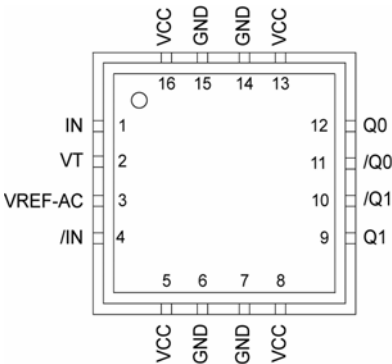
Ordering Information⁽¹⁾

Part Number	Package Type	Operating Range	Package Marking	Lead Finish
SY89851UMG	MLF-16	Industrial	851U with Pb-Free bar-line indicator	Pb-Free NiPdAu
SY89851UMGTR ⁽²⁾	MLF-16	Industrial	851U with Pb-Free bar-line indicator	Pb-Free NiPdAu

Notes:

- 1. Contact factory for die availability. Dice are guaranteed at T_A = 25°C, DC Electricals only.
- 2. Tape and Reel.

Pin Configuration



16-Pin MLF™ (MLF-16)

Pin Description

Pin Number	Pin Name	Pin Function
1,4	IN, /IN	Differential Inputs: This input pair is the differential signal input to the device. Inputs accept AC- or DC-coupled signals as small as 100mV (200mV _{pp}). Each pin terminates to a V _T pin through 50Ω. Note that these inputs will default to an indeterminate state if left open. Please refer to the "Input Interface Applications" section for more details.
2	VT	Input Termination Center-Tap: Each side of the differential input pair terminates to a V _T pin. The V _T pins provide a center-tap to a termination network for maximum interface flexibility. See "Input Interface Applications" section for more details.
3	VREF-AC	Reference Voltage: This output biases to V _{CC} –1.2V. It is used when AC-coupling the inputs (IN, /IN). For AC-coupled applications, connect V _{REF-AC} to the V _T pin and bypass with a 0.01μF low ESR capacitor to V _{CC} . Maximum sink/source current is ±1.5mA. See "Input Interface Applications" section for more details.
5,8,13,16	VCC	Positive Power Supply: Bypass with 0.1μF//0.01μF low ESR capacitors and place as close to each V _{CC} pin as possible.
12,11 9,10	Q0, /Q0, Q1, /Q1	Differential Outputs: These 100K LVPECL-compatible output pairs are the precision, low skew copies of the inputs. Unused output pairs may be left open. Terminate with 50Ω to V _{CC} –2V. See "LVPECL Output Interface Application" section for more details.
6,7,14,15	GND, Exposed Pad	Ground. GND and exposed pad must both be connected to the same ground plane.

Absolute Maximum Ratings⁽¹⁾

Supply Voltage (V_{CC})	-0.5V to +4.0V
Input Voltage (I_N , $/I_N$)	-0.5V to V_{CC}
LVPECL Output Current (I_{OUT})	
Continuous	 ± 50 mA
Surge	 ± 100 mA
Termination Current	
Source or sink current on V_T	 ± 100 mA
V_{REF-AC} Current	
Source or sink current	 ± 2 mA
Input Current	
Source or sink current on I_N , $/I_N$	 ± 50 mA
Lead Temperature (soldering, 20sec.)	 +260°C
Storage Temperature (T_s)	 -65°C to 150°C

Operating Ratings⁽²⁾

Supply Voltage (V_{CC})	 +2.375V to +2.625V
.....	 +3.0V to +3.6V
Ambient Temperature (T_A)	 -40°C to +85°C
Package Thermal Resistance ⁽³⁾	
MLF™ (θ_{JA})	
Still-Air	 60°C/W
MLF™ (ψ_{JB})	
Junction-to-Board	 33°C/W

DC Electrical Characteristics⁽⁴⁾

$T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$, unless otherwise stated.

Symbol	Parameter	Condition	Min	Typ	Max	Units
V_{CC}	Power Supply		2.375	2.5	2.625	V
			3.0	3.3	3.6	V
I_{CC}	Power Supply Current	No load, max. V_{CC}		32	45	mA
R_{IN}	Single-Ended Input Resistance (I_N -to- V_T)		45	50	55	Ω
R_{DIFF_IN}	Differential Input Resistance (I_N -to- $/I_N$)		90	100	110	Ω
V_{IH}	Input High Voltage (I_N , $/I_N$)	Note 5	$V_{CC} - 1.6$		V_{CC}	V
V_{IL}	Input Low Voltage (I_N , $/I_N$)		0		$V_{IH} - 0.1$	V
V_{IN}	Input Voltage Swing (I_N , $/I_N$)	See Figure 1a.	0.1		1.7	V
V_{DIFF_IN}	Differential Input Voltage Swing $ I_N - /I_N $	See Figure 1b.	0.2			V
V_{T_IN}	I_N -to- V_T (I_N , $/I_N$)				1.28	V
V_{REF-AC}	Output Reference Voltage		$V_{CC} - 1.3$	$V_{CC} - 1.2$	$V_{CC} - 1.1$	V

Notes:

1. Permanent device damage may occur if the absolute maximum ratings are exceeded. This is a stress rating only and functional operation is not implied at conditions other than those detailed in the operational sections of this data sheet. Exposure to absolute maximum ratings conditions for extended periods may affect device reliability.
2. The data sheet limits are not guaranteed if the device is operated beyond the operating ratings.
3. Package thermal resistance assumes exposed pad is soldered (or equivalent) to the devices most negative potential on the PCB. θ_{JA} and ψ_{JB} values are for a 4-layer board in still air, unless otherwise stated.
4. The circuit is designed to meet the DC specifications shown in the above table after thermal equilibrium has been established.
5. $V_{IH}(\text{min})$ not lower than 1.2V

100K LVPECL Output DC Electrical Characteristics⁽⁶⁾

$V_{CC} = 2.5V \pm 5\%$ or $3.3V \pm 10\%$; $T_A = -40^\circ C$ to $+85^\circ C$; $R_L = 50\Omega$ to $V_{CC} - 2V$, unless otherwise stated.

Symbol	Parameter	Condition	Min	Typ	Max	Units
V_{OH}	Output HIGH Voltage (Q, /Q)		$V_{CC} - 1.145$		$V_{CC} - 0.895$	V
V_{OL}	Output LOW Voltage (Q, /Q)		$V_{CC} - 1.945$		$V_{CC} - 1.695$	V
V_{OUT}	Output Voltage Swing (Q, /Q)	See Figure 1a.	550	800		mV
V_{DIFF_OUT}	Differential Output Voltage Swing (Q, /Q)	See Figure 1b.	1100	1600		mV

Note:

6. The circuit is designed to meet the DC specifications shown in the above table after thermal equilibrium has been established.

AC Electrical Characteristics⁽⁷⁾

$V_{CC} = 2.5V \pm 5\%$ or $3.3V \pm 10\%$, $R_L = 50\Omega$ to $V_{CC} - 2V$, $V_{IN} \geq 100mV$ ($200mV_{PP}$); $T_A = -40^\circ C$ to $+85^\circ C$, unless otherwise stated.

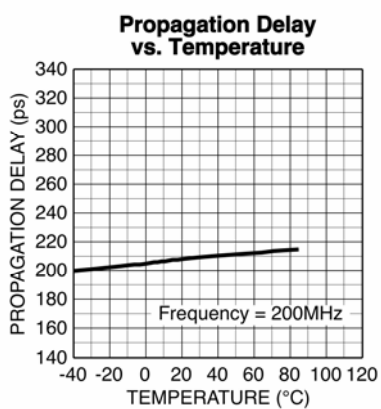
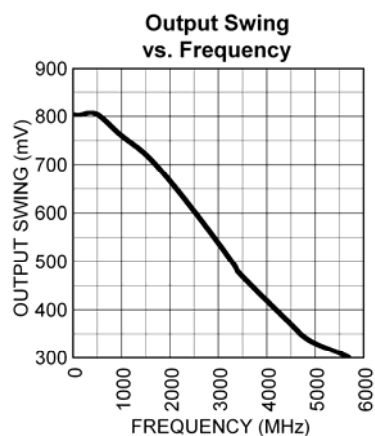
Symbol	Parameter	Condition	Min	Typ	Max	Units
f_{MAX}	Maximum Operating Frequency	NRZ Data	2.5	3.5		Gbps
		Clock	3	4		GHz
t_{pd}	Differential Propagation Delay	IN-to-Q	140	220	340	ps
$t_{pd} Tempco$	Δt_{pd} Temperature Coefficient			130		fs/ $^\circ C$
t_{SKEW}	Output-to-Output Skew	Note 8		6	20	ps
	Part-to-Part Skew	Note 9			120	ps
t_{JITTER}	Data					
	Random Jitter	Note 10			1	ps _{RMS}
	Deterministic Jitter	Note 11			10	ps _{PP}
	Clock					
t_r, t_f	Cycle-to-Cycle Jitter	Note 12			1	ps _{RMS}
	Total Jitter	Note 13			10	ps _{PP}
t_r, t_f	Output Rise/Fall Time (20% to 80%)	At full output swing	50	100	180	ps

Notes:

- High-frequency AC-parameters are guaranteed by design and characterization.
- Output-to-output skew is measured between two different outputs under identical input transitions.
- Part-to-part skew is defined for two parts with identical power supply voltages at the same temperature and with no skew of the edges at the respective inputs.
- Random jitter is measured with a K28.7 character pattern, measured at 2.5Gbps.
- Deterministic jitter is measured at 2.5Gbps, with both K28.5 and $2^{23} - 1$ PRBS pattern.
- Cycle-to-cycle jitter definition: the variation of periods between adjacent cycles, $T_n - T_{n-1}$ where T is the time between rising edges of the output signal.
- Total jitter definition: with an ideal clock input of frequency $< f_{MAX}$, no more than one output edge in 10^{12} output edges will deviate by more than the specified peak-to-peak jitter value.

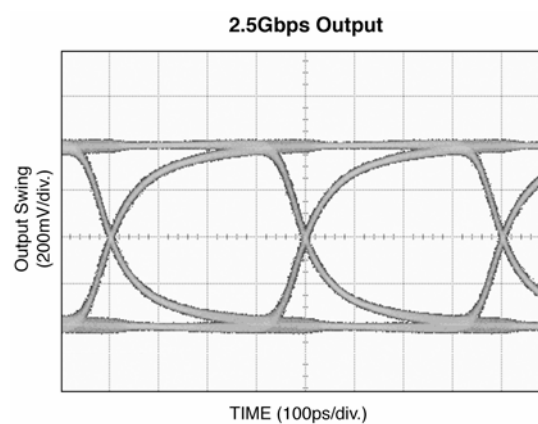
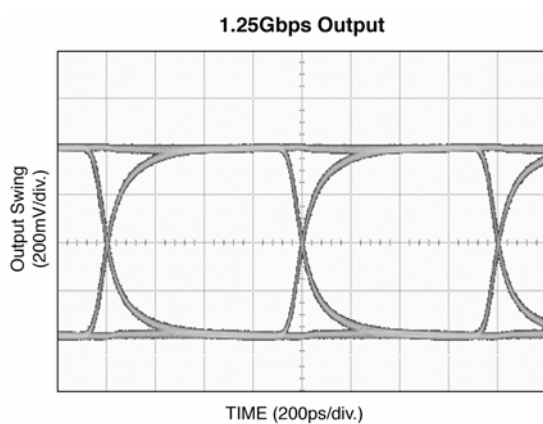
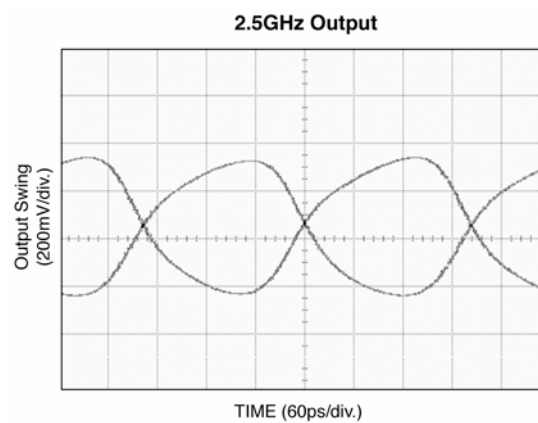
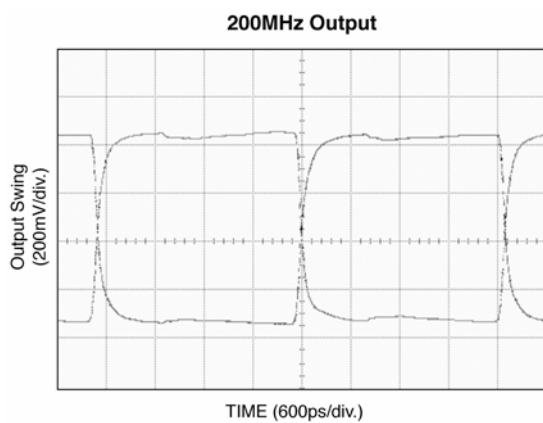
Typical Operating Characteristics

$V_{CC} = 3.3V$, $GND = 0V$, $V_{IN} = 100mV$ (200mV_{PP}), $R_L = 50\Omega$ to $V_{CC} - 2V$, $T_A = 25^\circ C$, unless otherwise stated.



Functional Characteristics

$V_{CC} = 3.3V$, $GND = 0V$, $V_{IN} = 100mV$ (200mV_{PP}), $R_L = 50\Omega$ to $V_{CC} - 2V$, $T_A = 25^\circ C$, unless otherwise stated.



Single-Ended and Differential Swings

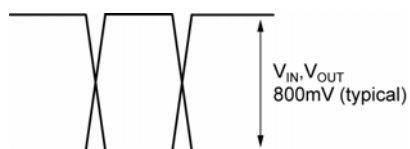


Figure 1a. Single-Ended Voltage Swing

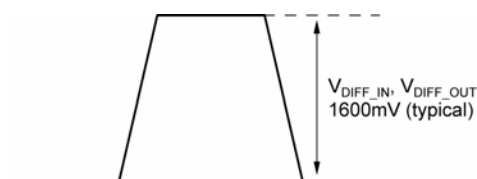
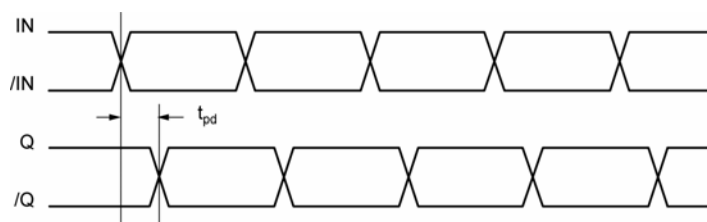


Figure 1b. Differential Voltage Swing

Timing Diagrams



Input and Output Stages

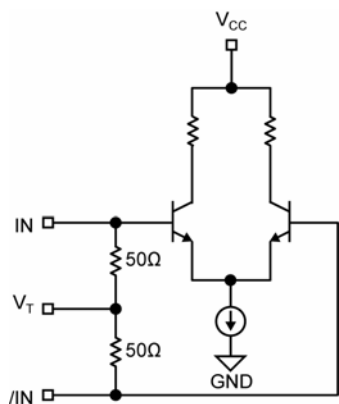


Figure 2a. Simplified Differential Input Stage

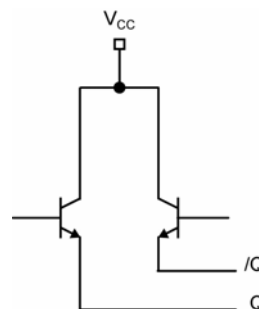


Figure 2b. Simplified LVPECL Output Stage

Input Interface Applications

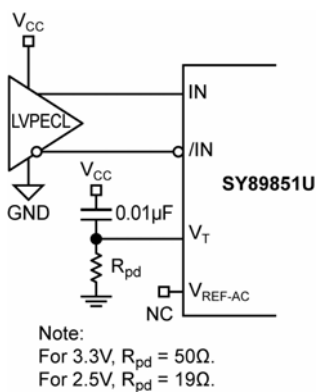


Figure 3a. LVPECL Interface
(DC-Coupled)

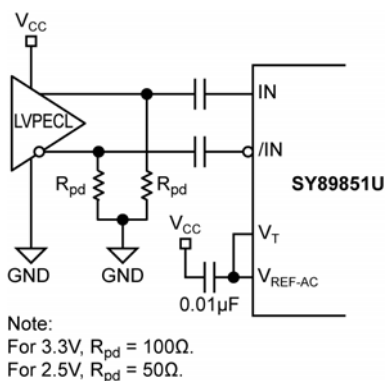
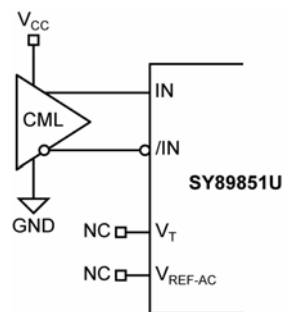


Figure 3b. LVPECL Interface
(AC-Coupled)



Optional: may connect V_T to V_{CC}

Figure 3c. CML Interface
(DC-Coupled)

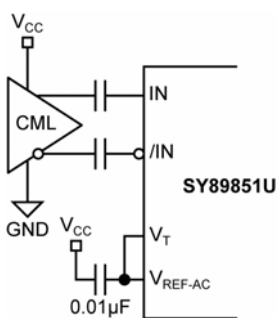


Figure 3d. CML Interface
(AC-Coupled)

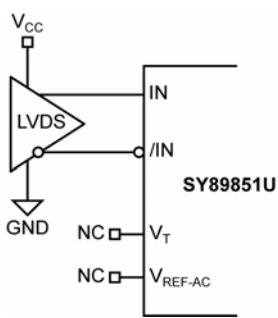


Figure 3e. LVDS Interface

LVPECL Output Interface Applications

LVPECL has high input impedance, very low output (open emitter) impedance, and small signal swing which result in low EMI. LVPECL is ideal for driving 50Ω- and 100Ω-controlled impedance transmission lines. There are several techniques for terminating

the LVPECL output including: Parallel Termination-Thevenin Equivalent, Parallel Termination (3-Resistor), and AC-Coupled Termination. Unused output pairs may be left floating. However, single-ended outputs must be terminated, or balanced.

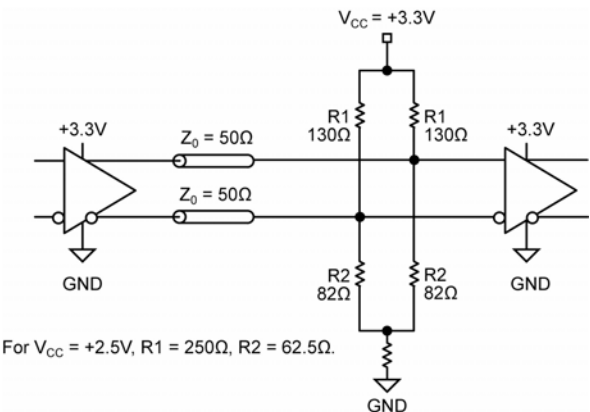


Figure 4a. Parallel Thevenin-Equivalent Termination

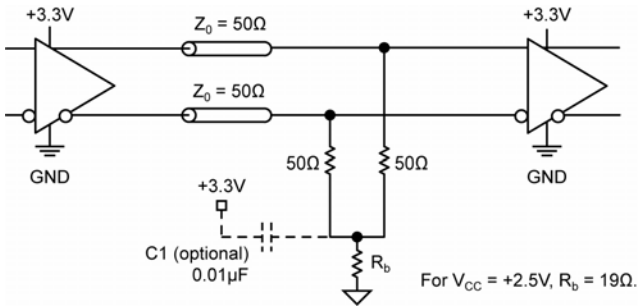
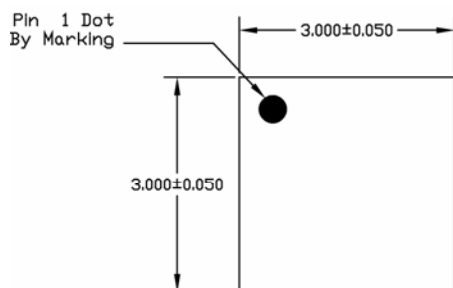


Figure 4b. Parallel Termination (3-Resistor)

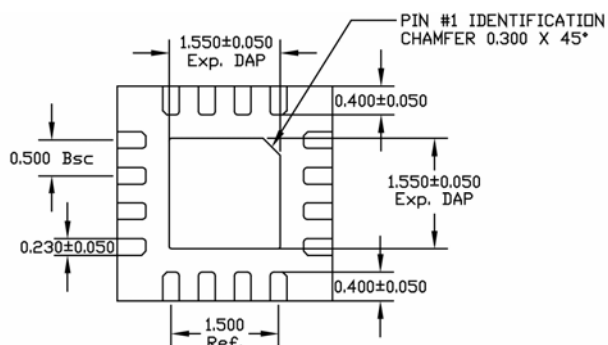
Related Product and Support Documentation

Part Number	Function	Data Sheet Link
SY58012U	5GHz, 1:2 LVPECL Fanout Buffer/Translator with Internal Input Termination	www.micrel.com/product-info/products/sy58012u.shtml
	MLF™ Application Note	www.amkor.com/products/notes_papers/MLF_AppNote.pdf
HBW Solutions	New Products and Applications	www.micrel.com/product-info/products/solutions.shtml

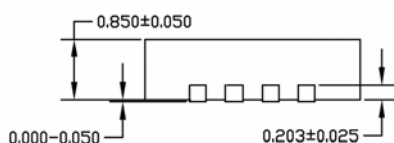
Package Information



TOP VIEW



BOTTOM VIEW



SIDE VIEW

NOTE:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. MAX. PACKAGE WARPAGE IS 0.05 mm.
3. MAXIMUM ALLOWABLE BURRS IS 0.076 mm IN ALL DIRECTIONS.
4. PIN #1 ID ON TOP WILL BE LASER/INK MARKED.

16-Pin MicroLeadFrame™ (MLF-16)

Package Notes:

1. Package meets Level 2 Moisture Sensitivity Classification.
2. All parts are dry-packaged before shipment.
3. Exposed pad must be soldered to a ground for proper thermal management.

MICREL, INC. 2180 FORTUNE DRIVE SAN JOSE, CA 95131 USA
TEL +1 (408) 944-0800 FAX +1 (408) 474-1000 WEB <http://www.micrel.com>

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